

# LT8650S

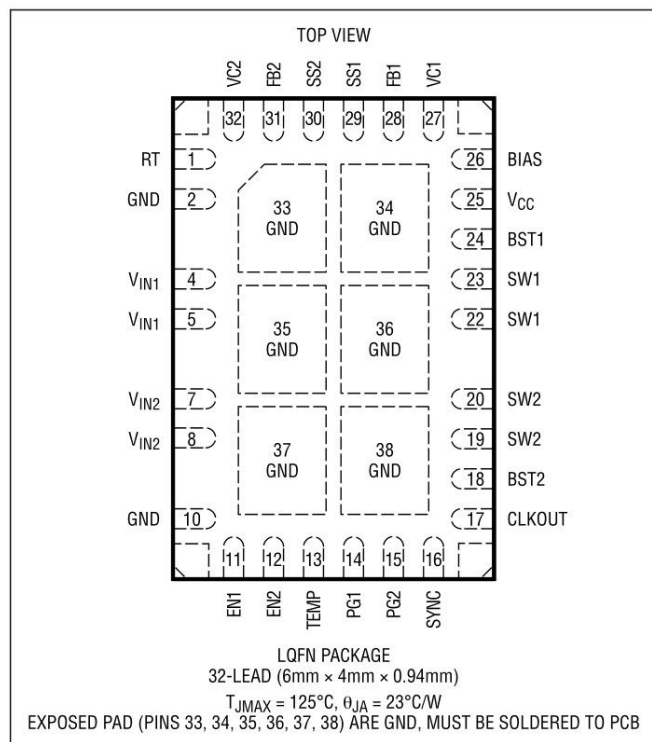
## ABSOLUTE MAXIMUM RATINGS

(Note 1)

$V_{IN1}$ , $V_{IN2}$ , EN/UV1, EN/UV2, PG1, PG2.....	42V
BIAS.....	30V
FB1, FB2, SS1, SS2 .....	4V
VC1, VC2.....	3.5V
SYNC.....	6V
Operating Junction Temperature Range (Note 2)	
LT8650SE .....	-40 to 125°C
LT8650SI .....	-40 to 125°C
Storage Temperature Range .....	-65 to 150°C
Maximum Reflow (Package Body) Temperature.....	260°C

Absolute Maximum Ratings will now show H Grade information.

## PIN CONFIGURATION



## ORDER INFORMATION

<http://www.linear.com/product/LT8650S#orderinfo>

PART NUMBER	PAD OR BALL FINISH	PART MARKING		PACKAGE** TYPE	MSL RATING	TEMPERATURE RANGE (SEE NOTE 2)
		DEVICE	FINISH CODE			
LT8650SEV#PBF	Au (RoHS)	8650SV	e4	LQFN (Laminate Package with QFN Footprint)	3	-40°C to 125°C
LT8650SIV#PBF						-40°C to 125°C

- Device temperature grade is indicated by a label on the shipping container.
- Pad or ball finish code is per IPC/JEDEC J-STD-609.
- Terminal Finish Part Marking: [www.linear.com/leadfree](http://www.linear.com/leadfree)
- Parts ending with PBF are RoHS and WEEE compliant.
- Recommended PCB Assembly and Manufacturing Procedures: [www.linear.com/module/pcbassembly](http://www.linear.com/module/pcbassembly)
- Package and Tray Drawings: [www.linear.com/packaging](http://www.linear.com/packaging)

\*\*The LT8650S package has the same dimensions as a standard 6mm × 4mm QFN package

Order Information updated to show H Grade. LT8650SHV#PBF and LT8650SHV#WPBF

## ELECTRICAL CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^{\circ}\text{C}$ .

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
Minimum Input Voltage	●		2.6	3	V
$V_{IN1}$ Quiescent Current in Shutdown	$V_{EN/UV1} = V_{EN/UV2} = 0\text{V}$ , $V_{SYNC} = 0\text{V}$	●	1.7	4	$\mu\text{A}$
$V_{IN1} + V_{CC}$ Quiescent Current in Sleep with Internal Compensation	$V_{EN/UV1} = V_{EN/UV2} = 2\text{V}$ , $V_{FB1} = V_{FB2} > 0.8\text{V}$ , $V_{VC1} = V_{VC2} = V_{CC}$ , $V_{SYNC} = 0\text{V}$	●	3.7	8	$\mu\text{A}$
$V_{IN1} + V_{CC}$ Quiescent Current in Sleep with External Compensation	$V_{EN/UV1} = V_{EN/UV2} = 2\text{V}$ , $V_{FB1} = V_{FB2} > 0.8\text{V}$ , $V_{VC1} = V_{VC2} = \text{Float}$ , $V_{SYNC} = 0\text{V}$	●	90	120	$\mu\text{A}$
				140	$\mu\text{A}$

Rev A

## ELECTRICAL CHARACTERISTICS

The ● denotes the specifications which apply over the full operating temperature range, otherwise specifications are at  $T_A = 25^\circ\text{C}$ .

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNITS
$V_{IN1} + V_{CC}$ Quiescent Current when Active	$V_{EN/UV1} = V_{EN/UV2} = 2\text{V}$ , $V_{FB1} = V_{FB2} > 0.8\text{V}$ , $V_{VC1} = V_{VC2} = V_{CC}$ , $V_{SYNC} = 3.4\text{V}$ ●		5	7	mA
$V_{IN}$ Current in Regulation	$V_{IN} = 12\text{V}$ , $V_{OUT} = 3.3\text{V}$ , Output Load = $100\mu\text{A}$ , $V_{VC1} = V_{VC2} = V_{CC}$ , $V_{SYNC} = 0\text{V}$ $V_{IN} = 12\text{V}$ , $V_{OUT} = 3.3\text{V}$ , Output Load = $1\text{mA}$ , $V_{VC1} = V_{VC2} = V_{CC}$ , $V_{SYNC} = 0\text{V}$		45 350	75 550	$\mu\text{A}$ $\mu\text{A}$
Feedback Reference Voltage	●	0.794 0.790	0.800 0.800	0.806 0.810	V V
Feedback Voltage Line Regulation	$V_{IN} = 4.0\text{V}$ to $36\text{V}$		0.004	0.02	%/V
Feedback Pin Input Current	$V_{FB} = 0.8\text{V}$	-20		20	nA
Minimum On-Time	$I_{LOAD} = 3\text{A}$ , $SYNC = 3.4\text{V} \Rightarrow 2\text{V}$ ●		40	60	ns
Oscillator Frequency	$R_T = 133\text{k}$ ● $R_T = 35.7\text{k}$ ● $R_T = 15\text{k}$ ●	270 <del>0.95</del> 1.85	300 0.94 2.00	330 <del>1.05</del> 2.15	kHz MHz MHz
Top Power NMOS Current Limit	●	10	12	14	A
Bottom Power NMOS Current Limit		6.5	8.5	10.5	A
SW Leakage Current	$V_{IN} = 42\text{V}$ , $V_{SW} = 0\text{V}$ , $42\text{V}$	-2		2	$\mu\text{A}$
EN/UV Pin Threshold	EN/UV Falling ●	0.7	0.74	0.78	V
EN/UV Pin Hysteresis			30		mV
EN/UV Pin Current	$V_{EN/UV} = 2\text{V}$	-20		20	nA
PG Upper Threshold Offset from $V_{FB}$	$V_{FB}$ Falling ●	<del>5.5</del> 5.4	<del>7.5</del> 7.2	9	%
PG Lower Threshold Offset from $V_{FB}$	$V_{FB}$ Rising ●	<del>0.5</del> -9.3	-7.5	<del>6</del> -5.7	%
PG Hysteresis			0.3		%
PG Leakage	$V_{PG} = 12\text{V}$	-40		40	nA
PG Pull-Down Resistance	$V_{PG} = 0.1\text{V}$ ●		600	1200	Ohm
SYNC Threshold	SYNC DC and Clock Low Level Voltage SYNC Clock High Level Voltage SYNC DC High Level Voltage	0.4		1.5 2.8	V V V
SYNC Pin Current	$V_{SYNC} = 6\text{V}$		120		$\mu\text{A}$
SS Source Current	●	1.0	2.0	3.0	$\mu\text{A}$
SS Pull-Down Resistance	Fault Condition, $SS = 0.1\text{V}$		200		$\Omega$
Error Amplifier Transconductance	$V_C = 1.25\text{V}$		0.9		mS
VC Source Current	$V_{FB} = 0.6\text{V}$ , $V_{VC} = 1.25\text{V}$		<del>170</del>	185	$\mu\text{A}$
VC Sink Current	$V_{FB} = 1.0\text{V}$ , $V_{VC} = 1.25\text{V}$		<del>170</del>	185	$\mu\text{A}$
VC Pin to Switch Current Gain			9.6		A/V
TEMP Output Voltage	$I_{TEMP} = 0\mu\text{A}$ , Temperature = $25^\circ\text{C}$ $I_{TEMP} = 0\mu\text{A}$ , Temperature = $125^\circ\text{C}$	<del>190</del> <del>1100</del>	250 1200	<del>310</del> <del>1300</del>	mV mV

**Note 1:** Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

**Note 2:** The LT8650SE is guaranteed to meet performance specifications from  $0^\circ\text{C}$  to  $125^\circ\text{C}$  junction temperature. Specifications over the  $-40^\circ\text{C}$  to  $125^\circ\text{C}$  operating junction temperature range are assured by design, characterization, and correlation with statistical process controls. The LT8650SI is guaranteed over the full  $-40^\circ\text{C}$  to  $125^\circ\text{C}$  operating junction temperature range. High junction temperatures degrade operating lifetimes. Operating lifetime is derated at junction temperatures greater

than  $125^\circ\text{C}$ . The junction temperature ( $T_J$ , in  $^\circ\text{C}$ ) is calculated from the ambient temperature ( $T_A$  in  $^\circ\text{C}$ ) and power dissipation ( $P_D$ , in Watts) according to the formula:

$$T_J = T_A + (P_D \cdot \theta_{JA}) \text{ where } \theta_{JA} \text{ (in } ^\circ\text{C/W) is the package thermal impedance.}$$

**Note 3:** This IC includes overtemperature protection that is intended to protect the device during overload conditions. Junction temperature will exceed  $150^\circ\text{C}$  when overtemperature protection is active. Continuous operation above the specified maximum operating junction temperature will reduce lifetime.